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Technical data sheet High Density Polyethylene BLOW MOULDING Produced in Europe

## Polymers

## **Description**

Aceso® HDPE 5502 R3 is a high density polyethylene (HDPE) with good compromise between stiffness and Environmental Stress Crack Resistance (ESCR). It has been specifically designed for the manufacture of blow molded packaging for pharmaceutical products and cosmetics liquids. However it is recommended to contact your local sales representative to obtain specific information and individual certificates regarding compliance to regulations.

Aceso® HDPE 5502 R3 is a pellet grade and contains antioxidants.

## **Characteristics**

Property	Method	Unit	Typical value (*)
Density	ISO 1183	g/cm³	0.954
Melt Flow Rate (190°C/21.6 kg)	ISO 1133/G	g/10 min	22
ESCR Antarox 100%	ASTM D 1693B	h	$F_{50} = 60$
Notched Charpy Impact Resistance 23°C	ISO 179-1	kJ/m²	16

<sup>(\*)</sup> Data not intended for specification purposes

## Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

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